			T					_	0 / 1 / 0 0		
PCN Number:			20160119002				PCN Date:		2/4/2016		
Title:		Datasheet fo									
<b>Customer Contact:</b>			PCN Manager	PCN Manager				<b>Dept:</b> Quality Services			
Chan	ge Ty	/pe:									
Assembly Site					Design Wafer Bum						
	Assembly Process			X	Data Sheet		Wafer Bump Material				
Assembly Materials			ıls		Part number change		Wafer	Vafer Bump Process			
	Mechanical Specification				Test Site		Wafer	er Fab Site			
	Packing/Shipping/Labeling				Test Process		Wafer	afer Fab Materials			
						Wafer	Wafer Fab Process				
Notification Details											
Desci	riptio	n of Change	:								
				nou	ncing an information only no	otifi	cation e	etc.			
Texas Instruments Incorporated is announcing an information only notification etc.											
The product datasheet(s) is being updated as summarized below.											
p. taatt aatabricot(b) is being aparted as sammanzed below											
The following change history provides further details.											
_	Texa										
	INST	S RUMENTS							INA219		
					SBOS448G – AUG	UST 2	008-REVISE	D DECEN	MBER 2015		
Chan	iges fro	om Revision F (Se	ptember 2011) to I	Revi	sion G				Page		
• A	Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation										
S	section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and										
	Mechanical, Packaging, and Orderable Information section										
	Updated Bus Timing Diagram Definitions table. I <sup>2</sup> C timing table values were previously based on simulation and not										
	iaracie	rized							6		
The datasheet number will be changing.											
Device Family			in se enangin		Change From:		Ch	ange	To:		
INA219				SBOS448F		SBOS448G					
1101213					32001101				7001100		
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/INA219											
neep.//www.encom/produce/invazio											
Reason for Change:											
To more accurately reflect device characteristics.											
Ambia	:t-	d immed at an	Fit Forms F		eties Ovelity or Beliebilit			- /		١.	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
	No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									es to	
Changes to product identification resulting from this PCN:											
Chan	ges t	o product id	entification	res	ulting from this PCN:						
None.											
Produ	uct A	ffected:									
INA2	19AI	D	INA219AIDC	٧R	INA219AIDCNRG4	I	NA219A	IDCN	IT		
		DCNTG4	INA219AIDR		INA219BID	I	NA219E	BIDCN	IR		
		DCNT	INA219BIDR								
					1						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com